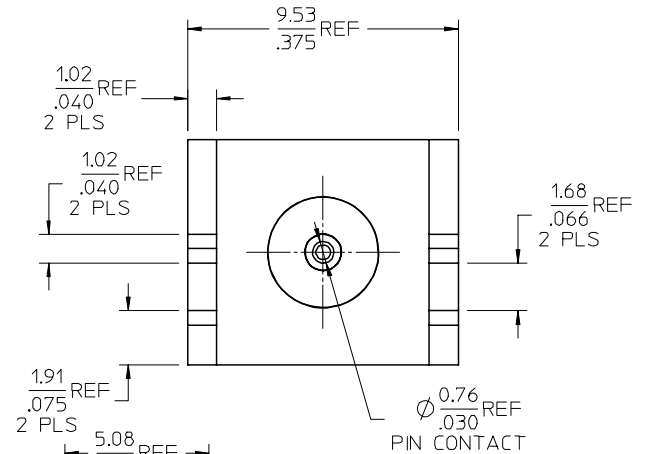
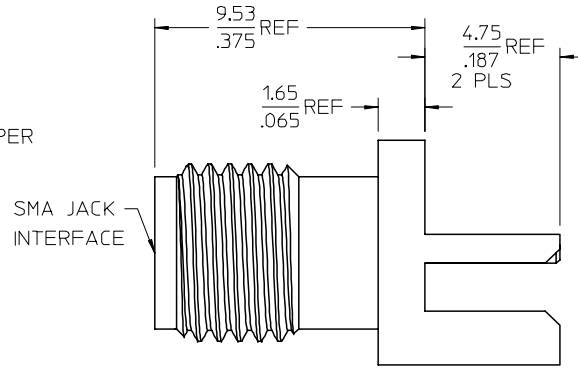


MATERIALS AND FINISHES

BODY BRASS
PLATED GOLD

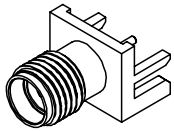
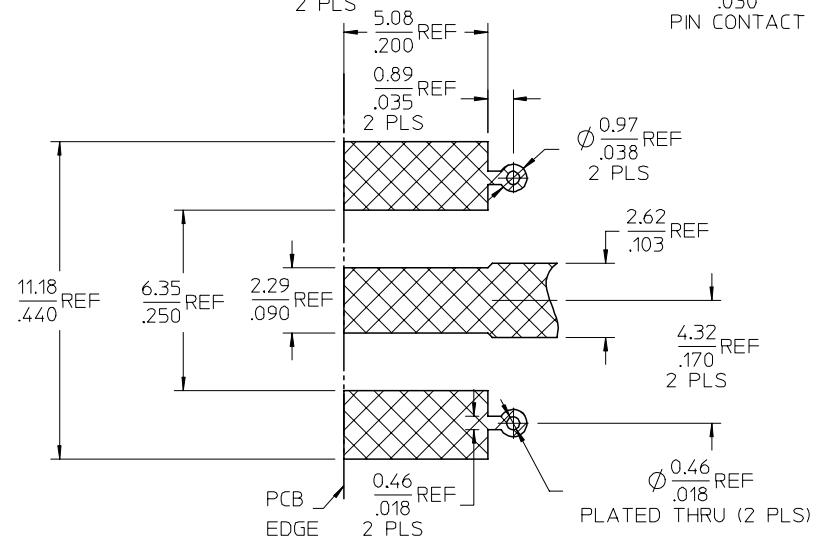
CENTER CONTACT BERYLLIUM COPPER
PLATED GOLD

INSULATOR TEFLON



RECOMMENDED MOUNTING PAD

BASE WIDTH: 9.53(.375)
BOARD THICKNESS: 1.57(.062)
BOARD MATERIAL: FR4 W/28 g(1.0 OZ) COPPER
ON BOTTOM (GROUND) SIDE



PS-89675-2820	ELEC/MECH PERFORMANCE
MIL-STD-348A, FIG. 310.2	INTERFACE
SPECIFICATION	DESCRIPTION

73251-1152	TRAY (20 PIECES)
73251-1151	P/N 73251-1150 ONE PER BAG
73251-1150	TRAY (80 PIECES)
PART NO.	PACKAGING

CHG: TABULATED
73251-1150
PACKAGING FOR -1152
WAS 73251-1150
BY TRAY (20 CAVY)
EC NO: URF2008-0012
2007/07/09
DRWN:SSHAH
CHKD:FLAHERTY
APPR:JMLENER
2007/07/09
DESCRIPTION
REV: A3

QUALITY SYMBOLS
=0
=0

GENERAL TOLERANCES (UNLESS SPECIFIED)	
4 PLACES	± .005
3 PLACES	± .004
2 PLACES	± .003
1 PLACE	± .002
ANGULAR ± 2°	

DIMENSION STYLE	
MM/IN	
DRAWN BY	TEF
DATE	2002/06/27
CHECKED BY	SSS
DATE	2002/06/27
APPROVED BY	GMH
DATE	2002/06/27

SCALE DESIGN UNITS THIRD ANGLE PROJECTION

SMA JACK, EDGE MOUNT
50 OHMS, EWR-1764
SMA-J/PCB

MATERIAL NO. SD-73251-115
DOCUMENT NO. SD-73251-115
SHEET NO. 1 OF 1

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

SEE TABLE

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